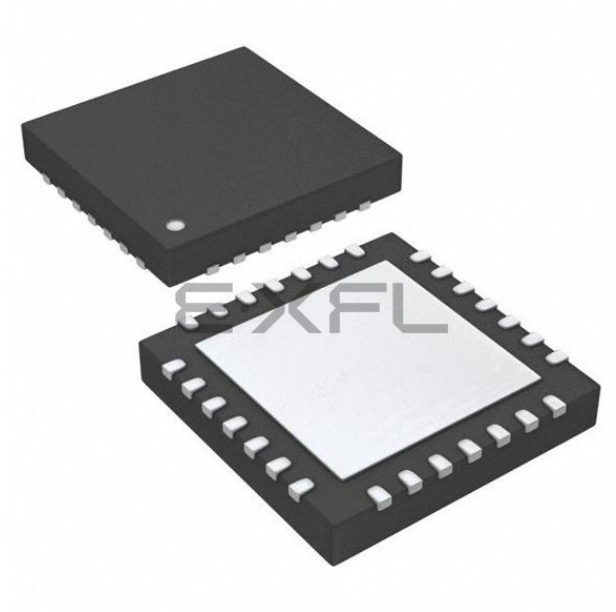

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	21
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 10x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx120f032b-i-ml

TABLE 6: PIN NAMES FOR 28-PIN USB DEVICES

28-PIN QFN (TOP VIEW)(1,2,3,4)

PIC32MX210F016B
PIC32MX220F032B
PIC32MX230F064B
PIC32MX230F256B
PIC32MX250F128B
PIC32MX270F256B

28 1

Pin #	Full Pin Name	Pin #	Full Pin Name
1	PGED1/AN2/C1IND/C2INB/C3IND/RPB0/PMD0/RB0	15	TDO/RPB9/SDA1/CTED4/PMD3/RB9
2	PGEC1/AN3/C1INC/C2INA/RPB1/CTED12/PMD1/RB1	16	VSS
3	AN4/C1INB/C2IND/RPB2/SDA2/CTED13/PMD2/RB2	17	VCAP
4	AN5/C1INA/C2INC/RTCC/RPB3/SCL2/PMWR/RB3	18	PGED2/RPB10/D+/CTED11/RB10
5	VSS	19	PGEC2/RPB11/D-/RB11
6	OSC1/CLKI/RPA2/RA2	20	VUSB3V3
7	OSC2/CLKO/RPA3/PMA0/RA3	21	AN11/RPB13/CTPLS/PMRD/RB13
8	SOSCI/RPB4/RB4	22	CVREFOUT/AN10/C3INB/RPB14/VBUSON/SCK1/CTED5/RB14
9	SOSCO/RPA4/T1CK/CTED9/PMA1/RA4	23	AN9/C3INA/RPB15/SCK2/CTED6/PMCS1/RB15
10	VDD	24	AVSS
11	TMS/RPB5/USBID/RB5	25	AVDD
12	VBUS	26	$\overline{\text{MCLR}}$
13	TDI/RPB7/CTED3/PMD5/INT0/RB7	27	PGED3/VREF+/CVREF+/AN0/C3INC/RPA0/CTED1/PMD7/RA0
14	TCK/RPB8/SCL1/CTED10/PMD4/RB8	28	PGEC3/VREF-/CVREF-/AN1/RPA1/CTED2/PMD6/RA1

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 11.3 "Peripheral Pin Select"** for restrictions.

2: Every I/O port pin (RAx-RCx) can be used as a change notification pin (CNAx-CNCx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: Shaded pins are 5V tolerant.

TABLE 1-1: PINOUT I/O DESCRIPTIONS

Pin Name	Pin Number(1)				Pin Type	Buffer Type	Description
	28-pin QFN	28-pin SSOP/ SPDIP/ SOIC	36-pin VTLA	44-pin QFN/ TQFP/ VTLA			
AN0	27	2	33	19	I	Analog	Analog input channels.
AN1	28	3	34	20	I	Analog	
AN2	1	4	35	21	I	Analog	
AN3	2	5	36	22	I	Analog	
AN4	3	6	1	23	I	Analog	
AN5	4	7	2	24	I	Analog	
AN6	—	—	3	25	I	Analog	
AN7	—	—	4	26	I	Analog	
AN8	—	—	—	27	I	Analog	
AN9	23	26	29	15	I	Analog	
AN10	22	25	28	14	I	Analog	
AN11	21	24	27	11	I	Analog	
AN12	20(2)	23(2)	26(2) 11(3)	10(2) 36(3)	I	Analog	
CLKI	6	9	7	30	I	ST/CMOS	External clock source input. Always associated with OSC1 pin function.
CLKO	7	10	8	31	O	—	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes. Always associated with OSC2 pin function.
OSC1	6	9	7	30	I	ST/CMOS	Oscillator crystal input. ST buffer when configured in RC mode; CMOS otherwise.
OSC2	7	10	8	31	O	—	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes.
SOSCI	8	11	9	33	I	ST/CMOS	32.768 kHz low-power oscillator crystal input; CMOS otherwise.
SOSCO	9	12	10	34	O	—	32.768 kHz low-power oscillator crystal output.
REFCLKI	PPS	PPS	PPS	PPS	I	ST	Reference Input Clock
REFCLKO	PPS	PPS	PPS	PPS	O	—	Reference Output Clock
IC1	PPS	PPS	PPS	PPS	I	ST	Capture Inputs 1-5
IC2	PPS	PPS	PPS	PPS	I	ST	
IC3	PPS	PPS	PPS	PPS	I	ST	
IC4	PPS	PPS	PPS	PPS	I	ST	
IC5	PPS	PPS	PPS	PPS	I	ST	

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
TTL = TTL input buffer; PPS = Peripheral Pin Select; — = N/A

Note 1: Pin numbers are provided for reference only. See the **"Pin Diagrams"** section for device pin availability.

2: Pin number for PIC32MX1XX devices only.

3: Pin number for PIC32MX2XX devices only.

6.0 RESETS

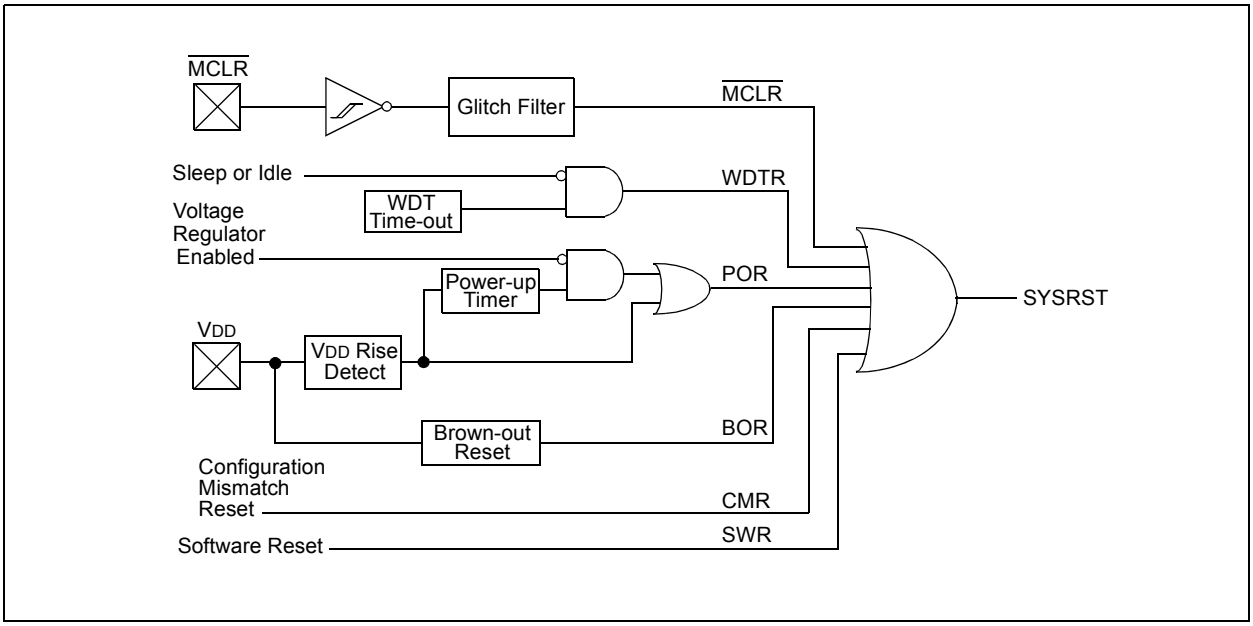
Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 7. "Resets"** (DS60001118), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The Reset module combines all Reset sources and controls the device Master Reset signal, SYSRST. The following is a list of device Reset sources:

- Power-on Reset (POR)
- Master Clear Reset pin ($\overline{\text{MCLR}}$)
- Software Reset (SWR)
- Watchdog Timer Reset (WDTR)
- Brown-out Reset (BOR)
- Configuration Mismatch Reset (CMR)

A simplified block diagram of the Reset module is illustrated in Figure 6-1.

FIGURE 6-1: SYSTEM RESET BLOCK DIAGRAM



NOTES:

REGISTER 10-11: U1CON: USB CONTROL REGISTER (CONTINUED)

bit 1 **PPBRST:** Ping-Pong Buffers Reset bit
1 = Reset all Even/Odd buffer pointers to the EVEN Buffer Descriptor banks
0 = Even/Odd buffer pointers are not Reset

bit 0 **USBEN:** USB Module Enable bit(4)
1 = USB module and supporting circuitry is enabled
0 = USB module and supporting circuitry is disabled

SOFEN: SOF Enable bit(5)
1 = SOF token is sent every 1 ms
0 = SOF token is disabled

Note 1: Software is required to check this bit before issuing another token command to the U1TOK register (see Register 10-15).

2: All host control logic is reset any time that the value of this bit is toggled.

3: Software must set RESUME for 10 ms if the part is a function, or for 25 ms if the part is a host, and then clear it to enable remote wake-up. In Host mode, the USB module will append a Low-Speed EOP to the RESUME signaling when this bit is cleared.

4: Device mode.

5: Host mode.

REGISTER 10-14: U1FRMH: USB FRAME NUMBER HIGH REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	U-0	U-0	U-0	U-0	R-0	R-0	R-0
	—	—	—	—	—	FRMH<2:0>		

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-3 **Unimplemented:** Read as '0'

bit 2-0 **FRMH<2:0>:** The Upper 3 bits of the Frame Numbers bits
The register bits are updated with the current frame number whenever a SOF TOKEN is received.

REGISTER 10-15: U1TOK: USB TOKEN REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	PID<3:0>(1)				EP<3:0>			

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7-4 **PID<3:0>:** Token Type Indicator bits(1)
1101 = SETUP (TX) token type transaction
1001 = IN (RX) token type transaction
0001 = OUT (TX) token type transaction
Note: All other values are reserved and must not be used.

bit 3-0 **EP<3:0>:** Token Command Endpoint Address bits
The four bit value must specify a valid endpoint.

Note 1: All other values are reserved and must not be used.

REGISTER 11-3: CNCONx: CHANGE NOTICE CONTROL FOR PORTx REGISTER (x = A, B, C)

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
	ON	—	SIDL	—	—	—	—	—
7:0	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

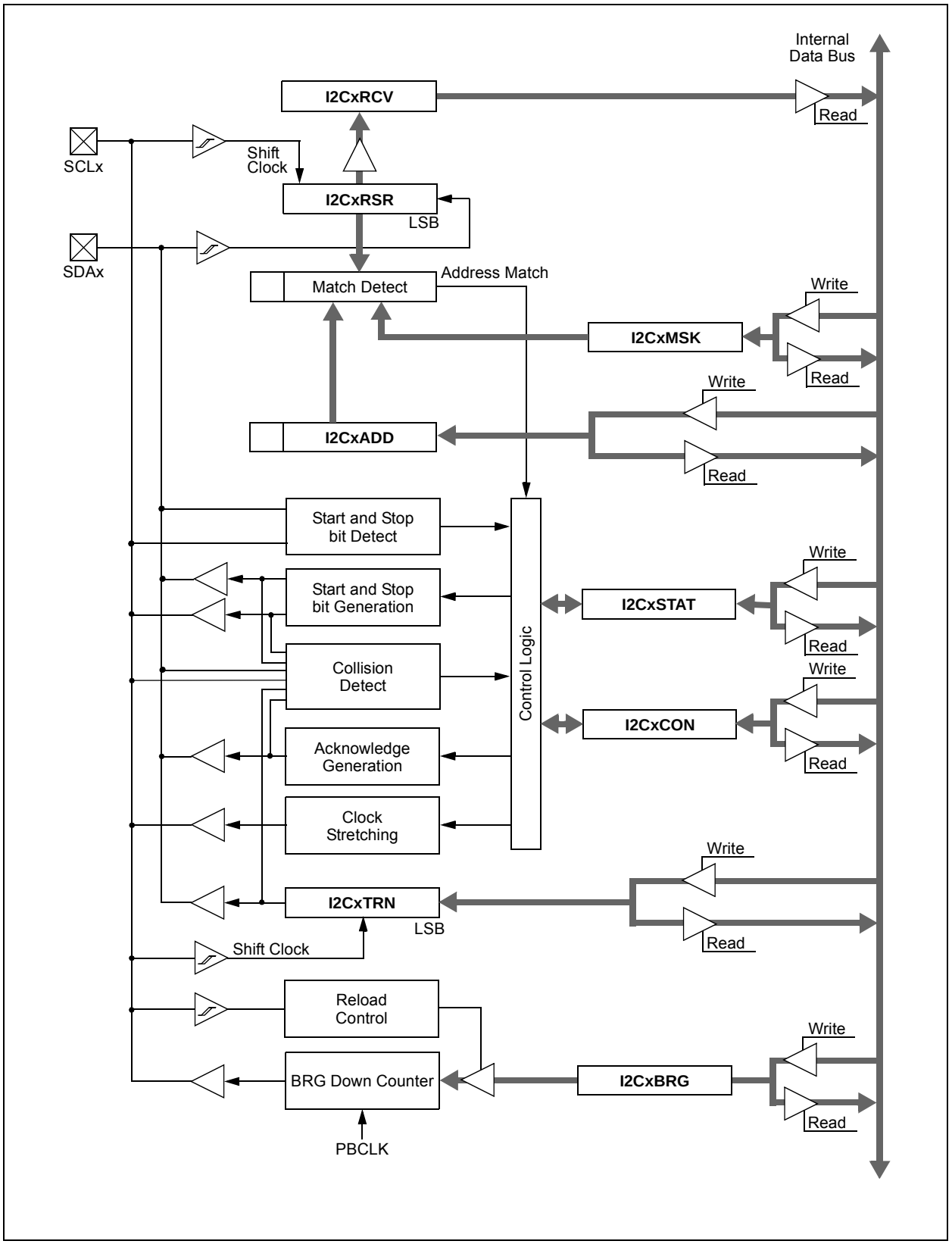
bit 15 **ON:** Change Notice (CN) Control ON bit
- 1 = CN is enabled
- 0 = CN is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **SIDL:** Stop in Idle Control bit
- 1 = Idle mode halts CN operation
- 0 = Idle does not affect CN operation

bit 12-0 **Unimplemented:** Read as '0'

FIGURE 18-1: I²C BLOCK DIAGRAM



REGISTER 18-1: I2CxCON: I^{2}C CONTROL REGISTER (CONTINUED)

bit 7 **GCEN:** General Call Enable bit (when operating as I^{2}C slave)
1 = Enable interrupt when a general call address is received in the I2CxRSR (module is enabled for reception)
0 = General call address is disabled

bit 6 **STREN:** SCLx Clock Stretch Enable bit (when operating as I^{2}C slave)
Used in conjunction with SCLREL bit.
1 = Enable software or receive clock stretching
0 = Disable software or receive clock stretching

bit 5 **ACKDT:** Acknowledge Data bit (when operating as I^{2}C master, applicable during master receive)
Value that is transmitted when the software initiates an Acknowledge sequence.
1 = Send a NACK during an Acknowledge sequence
0 = Send an ACK during an Acknowledge sequence

bit 4 **ACKEN:** Acknowledge Sequence Enable bit (when operating as I^{2}C master, applicable during master receive)
1 = Initiate Acknowledge sequence on SDAx and SCLx pins and transmit ACKDT data bit. Hardware clear at end of master Acknowledge sequence.
0 = Acknowledge sequence not in progress

bit 3 **RCEN:** Receive Enable bit (when operating as I^{2}C master)
1 = Enables Receive mode for I^{2}C. Hardware clear at end of eighth bit of master receive data byte.
0 = Receive sequence not in progress

bit 2 **PEN:** Stop Condition Enable bit (when operating as I^{2}C master)
1 = Initiate Stop condition on SDAx and SCLx pins. Hardware clear at end of master Stop sequence.
0 = Stop condition not in progress

bit 1 **RSEN:** Repeated Start Condition Enable bit (when operating as I^{2}C master)
1 = Initiate Repeated Start condition on SDAx and SCLx pins. Hardware clear at end of master Repeated Start sequence.
0 = Repeated Start condition not in progress

bit 0 **SEN:** Start Condition Enable bit (when operating as I^{2}C master)
1 = Initiate Start condition on SDAx and SCLx pins. Hardware clear at end of master Start sequence.
0 = Start condition not in progress

Note 1: When using 1:1 PBCLK divisor, the user's software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

REGISTER 18-2: I2CxSTAT: I^{2}C STATUS REGISTER (CONTINUED)

bit 4 **P:** Stop bit
1 = Indicates that a Stop bit has been detected last
0 = Stop bit was not detected last
Hardware set or clear when Start, Repeated Start or Stop detected.

bit 3 **S:** Start bit
1 = Indicates that a Start (or Repeated Start) bit has been detected last
0 = Start bit was not detected last
Hardware set or clear when Start, Repeated Start or Stop detected.

bit 2 **R_W:** Read/Write Information bit (when operating as I^{2}C slave)
1 = Read – indicates data transfer is output from slave
0 = Write – indicates data transfer is input to slave
Hardware set or clear after reception of I^{2}C device address byte.

bit 1 **RBF:** Receive Buffer Full Status bit
1 = Receive complete, I2CxRCV is full
0 = Receive not complete, I2CxRCV is empty
Hardware set when I2CxRCV is written with received byte. Hardware clear when software reads I2CxRCV.

bit 0 **TBF:** Transmit Buffer Full Status bit
1 = Transmit in progress, I2CxTRN is full
0 = Transmit complete, I2CxTRN is empty
Hardware set when software writes I2CxTRN. Hardware clear at completion of data transmission.

22.0 10-BIT ANALOG-TO-DIGITAL CONVERTER (ADC)

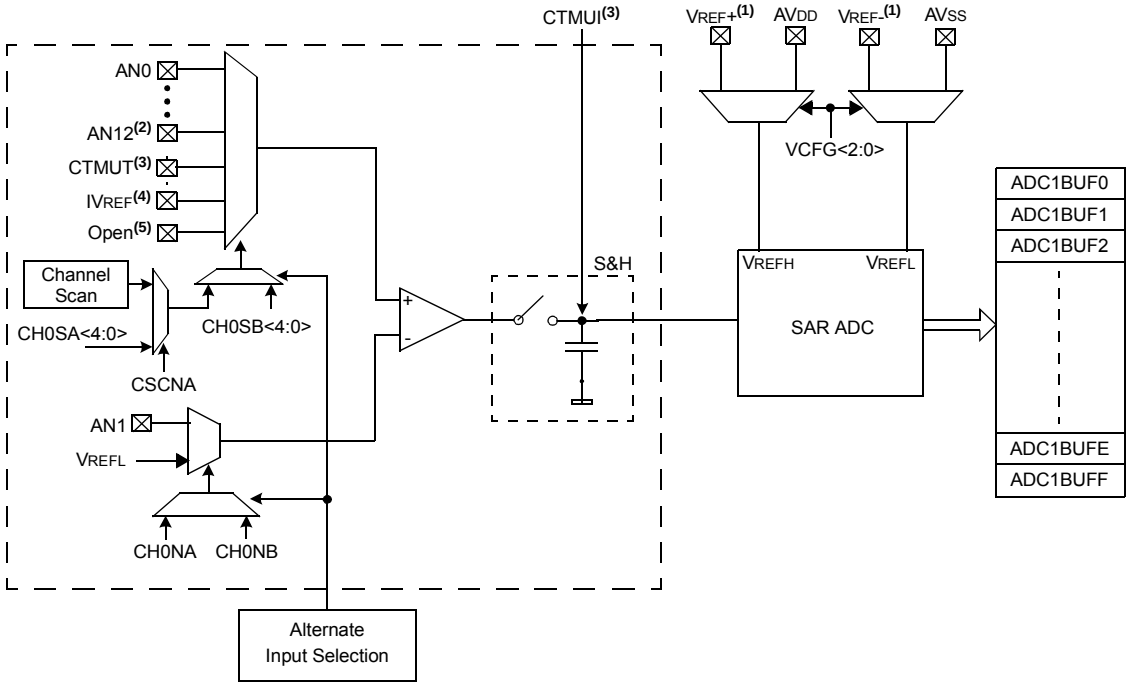
Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 17. "10-bit Analog-to-Digital Converter (ADC)"** (DS60001104), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The 10-bit Analog-to-Digital Converter (ADC) includes the following features:

- Successive Approximation Register (SAR) conversion
- Up to 1 Msps conversion speed
- Up to 13 analog input pins
- External voltage reference input pins
- One unipolar, differential Sample and Hold Amplifier (SHA)
- Automatic Channel Scan mode
- Selectable conversion trigger source
- 16-word conversion result buffer
- Selectable buffer fill modes
- Eight conversion result format options
- Operation during Sleep and Idle modes

A block diagram of the 10-bit ADC is illustrated in Figure 22-1. Figure 22-2 illustrates a block diagram of the ADC conversion clock period. The 10-bit ADC has up to 13 analog input pins, designated AN0-AN12. In addition, there are two analog input pins for external voltage reference connections. These voltage reference inputs may be shared with other analog input pins and may be common to other analog module references.

FIGURE 22-1: ADC1 MODULE BLOCK DIAGRAM



Note 1: VREF+ and VREF- inputs can be multiplexed with other analog inputs.

2: AN8 is only available on 44-pin devices. AN6, AN7, and AN12 are not available on 28-pin devices.

3: Connected to the CTMU module. See **Section 25.0 "Charge Time Measurement Unit (CTMU)"** for more information.

4: Internal precision voltage reference (1.2V).

5: This selection is only used with CTMU capacitive and time measurement.

22.1 ADC Control Registers

TABLE 22-1: ADC REGISTER MAP

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
9000	AD1CON1(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	FORM<2:0>			SSRC<2:0>			CLRASAM	—	ASAM	SAMP	DONE	0000
9010	AD1CON2(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	VCFG<2:0>			OFFCAL	—	CSCNA	—	—	BUFS	—	SMPI<3:0>				BUFM	ALTS	0000
9020	AD1CON3(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ADRC	—	—	SAMC<4:0>					ADCS<7:0>								0000
9040	AD1CHS(1)	31:16	CH0NB	—	—	—	CH0SB<3:0>				CH0NA	—	—	—	CH0SA<3:0>				0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
9050	AD1CSSL(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CSSL15	CSSL14	CSSL13	CSSL12	CSSL11	CSSL10	CSSL9	CSSL8	CSSL7	CSSL6	CSSL5	CSSL4	CSSL3	CSSL2	CSSL1	CSSL0	0000
9070	ADC1BUF0	31:16	ADC Result Word 0 (ADC1BUF0<31:0>)																0000
		15:0																	0000
9080	ADC1BUF1	31:16	ADC Result Word 1 (ADC1BUF1<31:0>)																0000
		15:0																	0000
9090	ADC1BUF2	31:16	ADC Result Word 2 (ADC1BUF2<31:0>)																0000
		15:0																	0000
90A0	ADC1BUF3	31:16	ADC Result Word 3 (ADC1BUF3<31:0>)																0000
		15:0																	0000
90B0	ADC1BUF4	31:16	ADC Result Word 4 (ADC1BUF4<31:0>)																0000
		15:0																	0000
90C0	ADC1BUF5	31:16	ADC Result Word 5 (ADC1BUF5<31:0>)																0000
		15:0																	0000
90D0	ADC1BUF6	31:16	ADC Result Word 6 (ADC1BUF6<31:0>)																0000
		15:0																	0000
90E0	ADC1BUF7	31:16	ADC Result Word 7 (ADC1BUF7<31:0>)																0000
		15:0																	0000
90F0	ADC1BUF8	31:16	ADC Result Word 8 (ADC1BUF8<31:0>)																0000
		15:0																	0000
9100	ADC1BUF9	31:16	ADC Result Word 9 (ADC1BUF9<31:0>)																0000
		15:0																	0000
9110	ADC1BUFA	31:16	ADC Result Word A (ADC1BUFA<31:0>)																0000
		15:0																	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for details.

REGISTER 25-1: CTMUCON: CTMU CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	EDG1MOD	EDG1POL	EDG1SEL<3:0>				EDG2STAT	EDG1STAT
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
	EDG2MOD	EDG2POL	EDG2SEL<3:0>				—	—
15:8	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	ON	—	CTMUSIDL	TGEN(1)	EDGEN	EDGSEQEN	IDISSEN(2)	CTTRIG
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	ITRIM<5:0>						IRNG<1:0>	

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31 **EDG1MOD:** Edge1 Edge Sampling Select bit
1 = Input is edge-sensitive
0 = Input is level-sensitive

bit 30 **EDG1POL:** Edge 1 Polarity Select bit
1 = Edge1 programmed for a positive edge response
0 = Edge1 programmed for a negative edge response

bit 29-26 **EDG1SEL<3:0>:** Edge 1 Source Select bits
1111 = C3OUT pin is selected
1110 = C2OUT pin is selected
1101 = C1OUT pin is selected
1100 = IC3 Capture Event is selected
1011 = IC2 Capture Event is selected
1010 = IC1 Capture Event is selected
1001 = CTED8 pin is selected
1000 = CTED7 pin is selected
0111 = CTED6 pin is selected
0110 = CTED5 pin is selected
0101 = CTED4 pin is selected
0100 = CTED3 pin is selected
0011 = CTED1 pin is selected
0010 = CTED2 pin is selected
0001 = OC1 Compare Event is selected
0000 = Timer1 Event is selected

bit 25 **EDG2STAT:** Edge2 Status bit
Indicates the status of Edge2 and can be written to control edge source
1 = Edge2 has occurred
0 = Edge2 has not occurred

Note 1: When this bit is set for Pulse Delay Generation, the EDG2SEL<3:0> bits must be set to '1110' to select C2OUT.

2: The ADC module Sample and Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitive measurement, must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to '1', performs this function. The ADC module must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.

3: Refer to the CTMU Current Source Specifications (Table 30-41) in **Section 30.0 "Electrical Characteristics"** for current values.

4: This bit setting is not available for the CTMU temperature diode.

REGISTER 25-1: CTMUCON: CTMU CONTROL REGISTER (CONTINUED)

bit 24 **EDG1STAT:** Edge1 Status bit
Indicates the status of Edge1 and can be written to control edge source
1 = Edge1 has occurred
0 = Edge1 has not occurred

bit 23 **EDG2MOD:** Edge2 Edge Sampling Select bit
1 = Input is edge-sensitive
0 = Input is level-sensitive

bit 22 **EDG2POL:** Edge 2 Polarity Select bit
1 = Edge2 programmed for a positive edge response
0 = Edge2 programmed for a negative edge response

bit 21-18 **EDG2SEL<3:0>:** Edge 2 Source Select bits
1111 = C3OUT pin is selected
1110 = C2OUT pin is selected
1101 = C1OUT pin is selected
1100 = PBCLK clock is selected
1011 = IC3 Capture Event is selected
1010 = IC2 Capture Event is selected
1001 = IC1 Capture Event is selected
1000 = CTED13 pin is selected
0111 = CTED12 pin is selected
0110 = CTED11 pin is selected
0101 = CTED10 pin is selected
0100 = CTED9 pin is selected
0011 = CTED1 pin is selected
0010 = CTED2 pin is selected
0001 = OC1 Compare Event is selected
0000 = Timer1 Event is selected

bit 17-16 **Unimplemented:** Read as '0'

bit 15 **ON:** ON Enable bit
1 = Module is enabled
0 = Module is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **CTMUSIDL:** Stop in Idle Mode bit
1 = Discontinue module operation when the device enters Idle mode
0 = Continue module operation when the device enters Idle mode

bit 12 **TGEN:** Time Generation Enable bit**(1)**
1 = Enables edge delay generation
0 = Disables edge delay generation

bit 11 **EDGEN:** Edge Enable bit
1 = Edges are not blocked
0 = Edges are blocked

Note 1: When this bit is set for Pulse Delay Generation, the EDG2SEL<3:0> bits must be set to '1110' to select C2OUT.

2: The ADC module Sample and Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitive measurement, must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to '1', performs this function. The ADC module must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.

3: Refer to the CTMU Current Source Specifications (Table 30-41) in **Section 30.0 "Electrical Characteristics"** for current values.

4: This bit setting is not available for the CTMU temperature diode.

REGISTER 27-1: DEVCFG0: DEVICE CONFIGURATION WORD 0 (CONTINUED)

bit 18-10 **PWP<8:0>:** Program Flash Write-Protect bits(3)

Prevents selected program Flash memory pages from being modified during code execution.
111111111 = Disabled
111111110 = Memory below 0x0400 address is write-protected
111111101 = Memory below 0x0800 address is write-protected
111111100 = Memory below 0x0C00 address is write-protected
111111011 = Memory below 0x1000 (4K) address is write-protected
111111010 = Memory below 0x1400 address is write-protected
111111001 = Memory below 0x1800 address is write-protected
111111000 = Memory below 0x1C00 address is write-protected
111110111 = Memory below 0x2000 (8K) address is write-protected
111110110 = Memory below 0x2400 address is write-protected
111110101 = Memory below 0x2800 address is write-protected
111110100 = Memory below 0x2C00 address is write-protected
111110011 = Memory below 0x3000 address is write-protected
111110010 = Memory below 0x3400 address is write-protected
111110001 = Memory below 0x3800 address is write-protected
111110000 = Memory below 0x3C00 address is write-protected
111101111 = Memory below 0x4000 (16K) address is write-protected
.
.
.
110111111 = Memory below 0x10000 (64K) address is write-protected
.
.
.
101111111 = Memory below 0x20000 (128K) address is write-protected
.
.
.
011111111 = Memory below 0x40000 (256K) address is write-protected
.
.
.
000000000 = All possible memory is write-protected

bit 9-5 **Reserved:** Write '1'

bit 4-3 **ICESEL<1:0>:** In-Circuit Emulator/Debugger Communication Channel Select bits(2)

11 = PGEC1/PGED1 pair is used
10 = PGEC2/PGED2 pair is used
01 = PGEC3/PGED3 pair is used
00 = PGEC4/PGED4 pair is used(2)

bit 2 **JTAGEN:** JTAG Enable bit(1)

1 = JTAG is enabled
0 = JTAG is disabled

bit 1-0 **DEBUG<1:0>:** Background Debugger Enable bits (forced to '11' if code-protect is enabled)

1x = Debugger is disabled
0x = Debugger is enabled

Note 1: This bit sets the value for the JTAGEN bit in the CFGCON register.

2: The PGEC4/PGED4 pin pair is not available on all devices. Refer to the **"Pin Diagrams"** section for availability.

3: The PWP<8:7> bits are only available on devices with 256 KB Flash.

TABLE 30-7: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD})

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp		
Param. No.	**Typical(2)**	**Max.**	**Units**	**Conditions**	
Power-Down Current (I_{PD}) (Notes 1, 5)					
DC40k	44	70	μA	-40°C	Base Power-Down Current
DC40l	44	70	μA	+25°C	
DC40n	168	259	μA	+85°C	
DC40m	335	536	μA	+105ºC	
Module Differential Current					
DC41e	5	20	μA	3.6V	Watchdog Timer Current: ΔI_{WDT} **(Note 3)**
DC42e	23	50	μA	3.6V	RTCC + Timer1 w/32 kHz Crystal: ΔI_{RTCC} **(Note 3)**
DC43d	1000	1100	μA	3.6V	ADC: ΔI_{ADC} **(Notes 3,4)**

Note 1: The test conditions for I_{PD} current measurements are as follows:

- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU is in Sleep mode, and SRAM data memory Wait states = 1
- No peripheral modules are operating, (ON bit = 0), but the associated PMD bit is set
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to V_{SS}
- $\overline{MCLR}$ = V_{DD}
- RTCC and JTAG are disabled

2: Data in the "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base I_{PD} current.

4: Test conditions for ADC module differential current are as follows: Internal ADC RC oscillator enabled.

5: I_{PD} electrical characteristics for devices with 256 KB Flash are only provided as Preliminary information.

TABLE 30-14: COMPARATOR VOLTAGE REFERENCE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Comments**
D312	TSET	Internal 4-bit DAC Comparator Reference Settling time	—	—	10	µs	See **Note 1**
D313	DACREFH	CVREF Input Voltage Reference Range	AVSS	—	AVDD	V	CVRSRC with CVRSS = 0
			VREF-	—	VREF+	V	CVRSRC with CVRSS = 1
D314	DVREF	CVREF Programmable Output Range	0	—	0.625 x DACREFH	V	0 to 0.625 DACREFH with DACREFH/24 step size
			0.25 x DACREFH	—	0.719 x DACREFH	V	0.25 x DACREFH to 0.719 DACREFH with DACREFH/32 step size
D315	DACRES	Resolution	—	—	DACREFH/24	—	CVRCON<CVRR> = 1
			—	—	DACREFH/32	—	CVRCON<CVRR> = 0
D316	DACACC	Absolute Accuracy(2)	—	—	1/4	LSB	DACREFH/24, CVRCON<CVRR> = 1
			—	—	1/2	LSB	DACREFH/32, CVRCON<CVRR> = 0

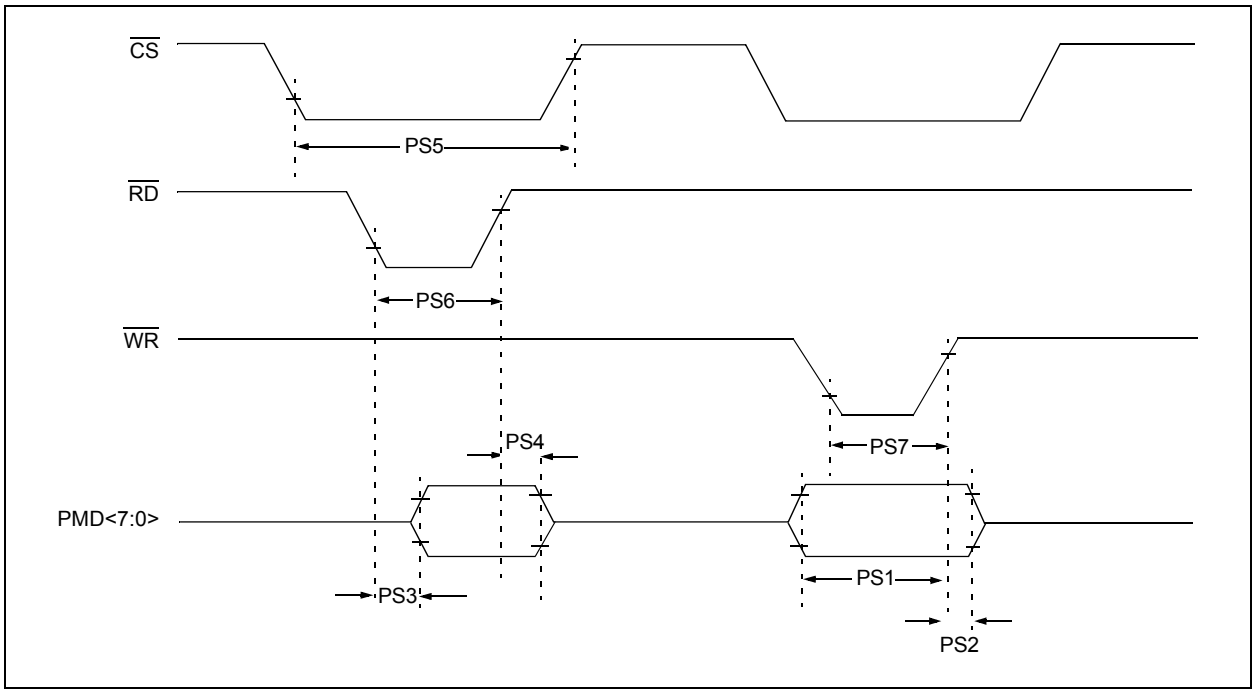
Note 1: Settling time was measured while CVRR = 1 and CVR<3:0> transitions from '0000' to '1111'. This parameter is characterized, but is not tested in manufacturing.

2: These parameters are characterized but not tested.

TABLE 30-15: INTERNAL VOLTAGE REGULATOR SPECIFICATIONS

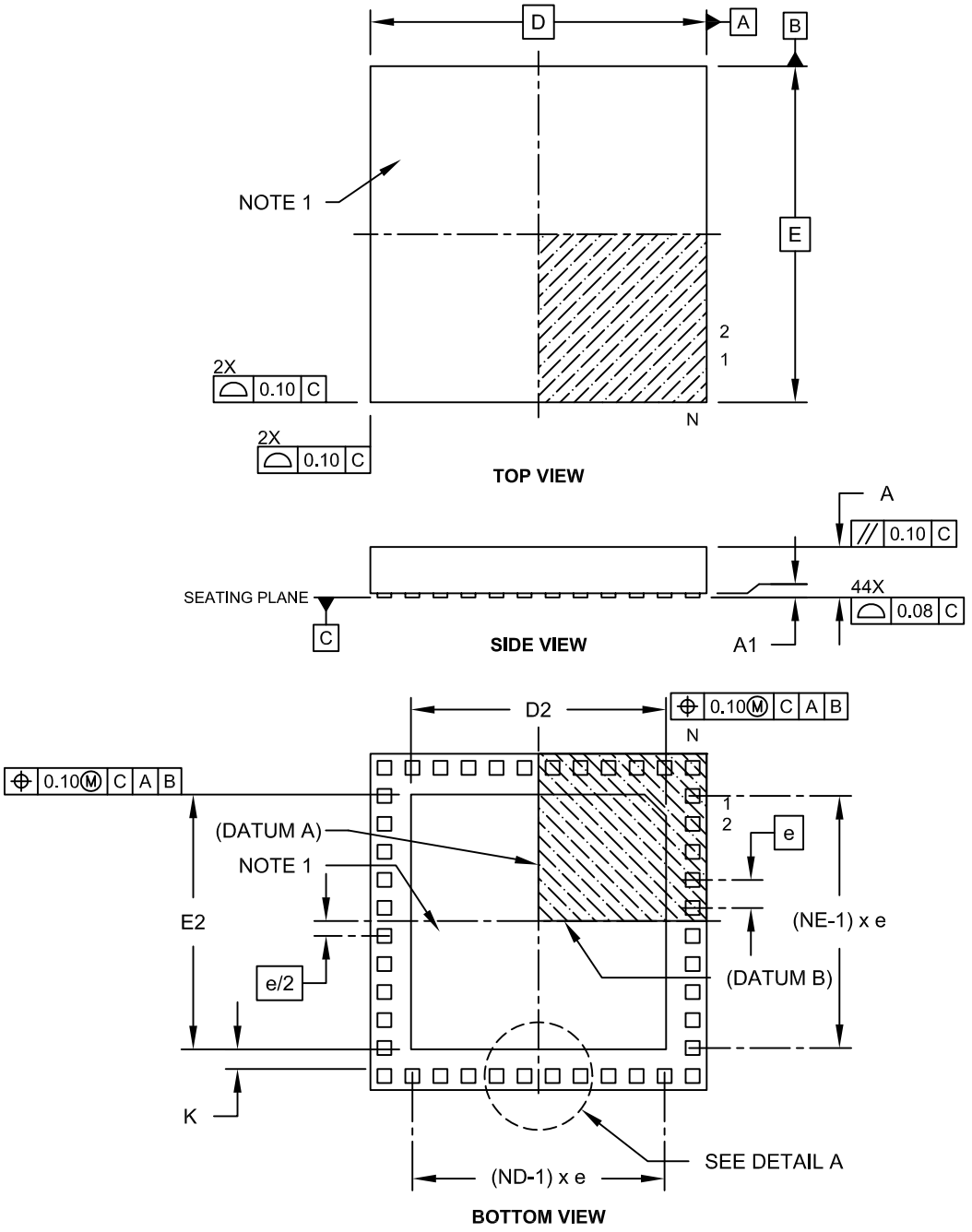
DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Comments**
D321	CEFC	External Filter Capacitor Value	8	10	—	µF	Capacitor must be low series resistance (1 ohm). Typical voltage on the VCAP pin is 1.8V.

FIGURE 30-20: PARALLEL SLAVE PORT TIMING



44-Terminal Very Thin Leadless Array Package (TL) – 6x6x0.9 mm Body With Exposed Pad [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-157C Sheet 1 of 2

Revision G (April 2015)

This revision includes the addition of the following devices:

- PIC32MX130F256B
- PIC32MX230F256B
- PIC32MX130F256D
- PIC32MX230F256D

The title of the document was updated to avoid confusion with the PIC32MX1XX/2XX/5XX 64/100-pin Family data sheet.

All peripheral SFR maps have been relocated from the Memory chapter to their respective peripheral chapters.

In addition, this revision includes the following major changes as described in Table A-6, as well as minor updates to text and formatting, which were incorporated throughout the document.

TABLE A-6: MAJOR SECTION UPDATES

Section	Update Description
32-bit Microcontrollers (up to 256 KB Flash and 64 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog	Added new devices to the family features (see Table 1 and Table 2). Updated pin diagrams to include new devices (see Pin Diagrams).
2.0 "Guidelines for Getting Started with 32-bit MCUs"	Updated these sections: **2.2 "Decoupling Capacitors"**, **2.3 "Capacitor on Internal Voltage Regulator (VCAP)"**, **2.4 "Master Clear (MCLR) Pin"**, **2.8.1 "Crystal Oscillator Design Consideration"**
4.0 "Memory Organization"	Added Memory Map for new devices (see Figure 4-6).
14.0 "Watchdog Timer (WDT)"	New chapter created from content previously located in the Special Features chapter.
30.0 "Electrical Characteristics"	Removed parameter D312 (TSET) from the Comparator Specifications (see Table 30-12). Added the Comparator Voltage Reference Specifications (see Table 30-13). Updated Table 30-12.

Revision H (July 2015)

This revision includes the following major changes as described in Table A-7, as well as minor updates to text and formatting, which were incorporated throughout the document.

TABLE A-7: MAJOR SECTION UPDATES

Section	Update Description
2.0 "Guidelines for Getting Started with 32-bit MCUs"	**Section 2.9 "Sosc Design Recommendation"** was removed.
8.0 "Oscillator Configuration"	The Primary Oscillator (POSC) logic in the Oscillator diagram was updated (see Figure 8-1).
30.0 "Electrical Characteristics"	The Power-Down Current (IPD) DC Characteristics parameter DC40k was updated (see Table 30-7). **Table 30-9: "DC Characteristics: I/O Pin Input Injection current Specifications"** was added.